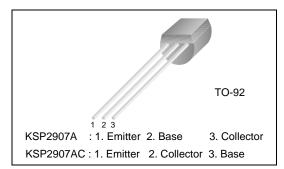
September 2006



# **KSP2907A PNP General Purpose Amplifier**

# **Features**

- Collector-Emitter Voltage: VCEO= 60V
- Collector Power Dissipation: Pc (max)=625mW
- Suffix "-C" means a Center Collector (1.Emitter 2.Collector 3.Base)
- Non suffix "-C" means a Side Collector (1.Emitter 2.Base 3.Collector)
- Available as PN2907A



# Absolute Maximum Ratings \* T<sub>a</sub> = 25°C unless otherwise noted

| Symbol           | Parameter                 | Value      | Units |
|------------------|---------------------------|------------|-------|
| V <sub>CBO</sub> | Collector-Base Voltage    | -60        | V     |
| V <sub>CEO</sub> | Collector-Emitter Voltage | -60        | V     |
| V <sub>EBO</sub> | Emitter-Base Voltage      | -5         | V     |
| I <sub>C</sub>   | Collector current         | -600       | mA    |
| TJ               | Junction Temperature      | +150       | °C    |
| T <sub>stg</sub> | Storage Temperature       | -55 ~ +150 | °C    |

These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.
These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Thermal Characteristics T\_=25°C unless otherwise noted

| Symbol          | Parameter                                       | Мах  | Units |
|-----------------|---|------|-------|
| P <sub>C</sub>  | Collector Power Dissipation, by $R_{\theta JA}$ | 625  | mW    |
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case(note1)     | 83.3 | °C/W  |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient(note2)  | 200  | °C/W  |

Note1. Infinite heat sink.

Note2. Minimum Land pad size.

## Electrical Characteristics \* T<sub>a</sub> = 25°C unless otherwise noted

| Symbol               | Parameter                            | Test Condition   | Min. | Тур. | Max. | Units |
|----------------------|--------------------------------------|--|------|------|------|-------|
| V <sub>(BR)CBO</sub> | Collector-Base Breakdown Voltage     | $I_{\rm C} = -10 \mu A, I_{\rm E} = 0$                                   | -60  |      |      | V     |
| V <sub>(BR)CEO</sub> | Collector-Emitter Breakdown Voltage  | I <sub>C</sub> = -10mA, I <sub>B</sub> = 0                               | -60  |      |      | V     |
| V <sub>(BR)EBO</sub> | Emitter-Base Breakdown Voltage       | $I_{E} = -10\mu A, I_{C} = 0$  | -5.0 |      |      | V     |
| I <sub>CBO</sub>     | Collector Cutoff Current             | $V_{CB} = -50V, I_E = 0$   |      |      | -10  | nA    |
| h <sub>FE</sub>      | DC Current Gain                      | V <sub>CE</sub> = -10V, I <sub>C</sub> = -0.1mA,                         | 75   |      |      |       |
|                      |                                      | $V_{CE} = -10V, I_{C} = -1mA,$   | 100  |      |      |       |
|                      |                                      | $V_{CE} = -10V, I_{C} = -10mA,$  | 100  |      |      |       |
|                      |                                      | V <sub>CE</sub> = -10V, I <sub>C</sub> = -150mA,                         | 100  |      | 300  |       |
|                      |                                      | $V_{CE} = -10V, I_{C} = -500mA,$   | 50   |      |      |       |
| V <sub>CE(sat)</sub> | Collector-Emitter Saturation Voltage | I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA                          |      |      | -0.4 | V     |
|                      |                                      | I <sub>C</sub> = -500mA, I <sub>B</sub> = -50mA                          |      |      | -1.6 | V     |
| V <sub>BE(sat)</sub> | Base-Emitter Saturation Voltage      | I <sub>C</sub> = -150mA, I <sub>B</sub> = -15mA                          |      |      | -1.3 | V     |
| ()                   |                                      | $I_{\rm C} = -500$ mA, $I_{\rm B} = -50$ mA                              |      |      | -2.6 | V     |
| C <sub>obo</sub>     | Output Capacitance                   | V <sub>CB</sub> = -10V, I <sub>E</sub> = 0, f = 1.0MHz                   |      |      | 8    | pF    |
| f <sub>T</sub>       | Current Gain Bandwidth Product       | $I_{\rm C} = -50$ mA, $V_{\rm CE} = -20$ V,                              | 200  |      |      | MHz   |
|                      |                                      | f = 100MHz   |      |      |      |       |
| <sup>t</sup> ON      | Turn On Time                         | V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA, I <sub>B1</sub> = -15mA |      |      | 45   | ns    |
| OFF                  | Turn Off Time                        | $V_{CC}$ = -6V, $I_{C}$ = -150mA, $I_{B1}$ = $I_{B1}$ = -15mA            |      |      | 100  | ns    |

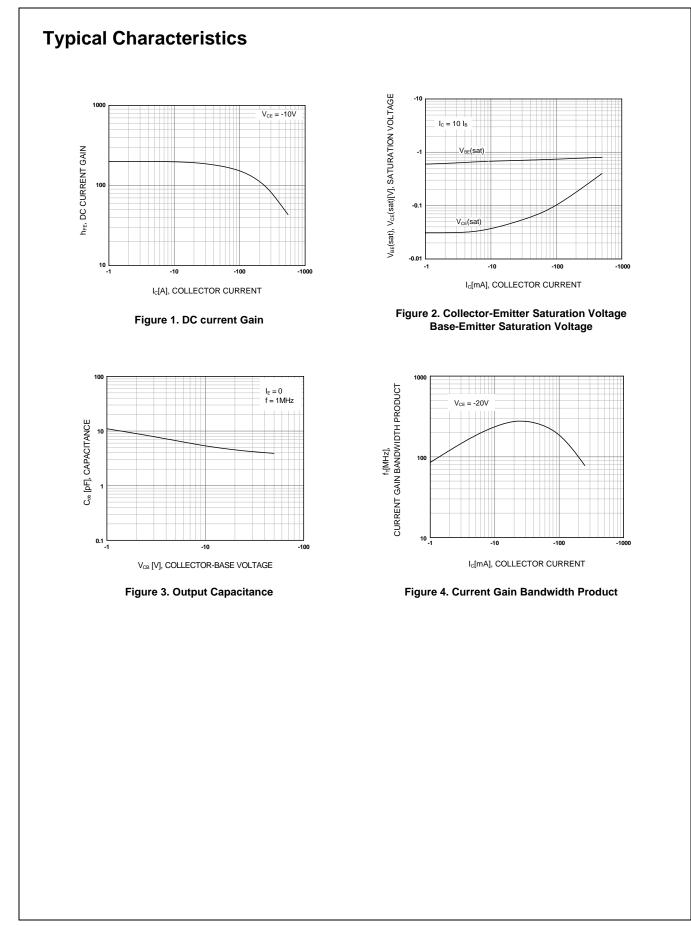
se Test: Pulse Width≤300us, Duty Cyc

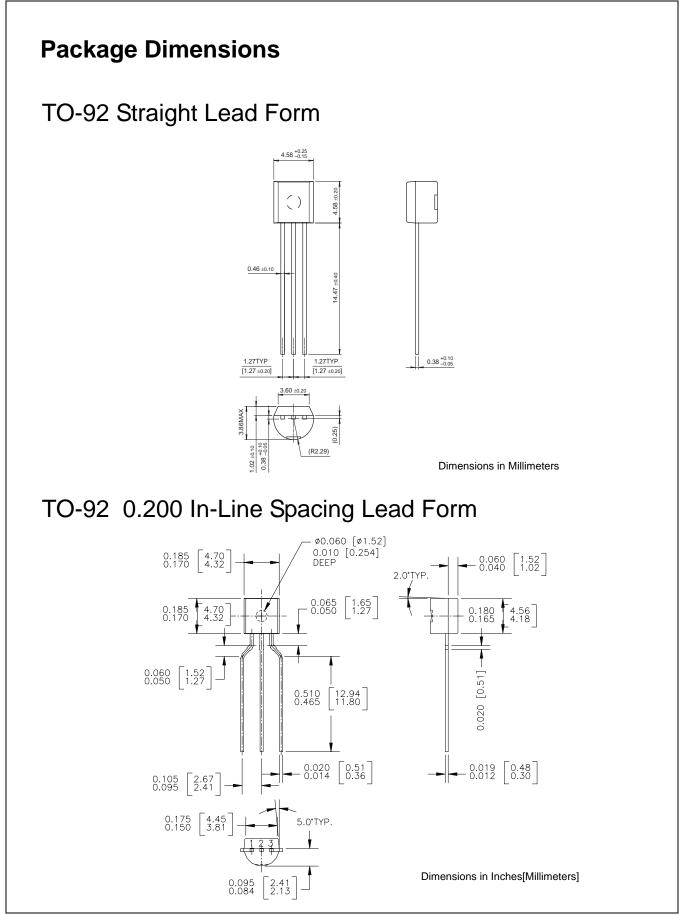
Downloaded from Elcodis.com electronic components distributor

# Package Marking and Ordering Information

| Device(note) | Device Marking | Package | Packing Method | Qty(pcs) | Pin Definitions              |
|--------------|----------------|---------|----------------|----------|------------------------------|
| KSP2907ABU   | KSP2907A       | TO-92   | BULK           |          | 1.Emitter 2.Base 3.Collector |
| KSP2907ACBU  | KSP2907AC      | TO-92   | BULK           |          | 1.Emitter 2.Collector 3.Base |
| KSP2907ATA   | KSP2907A       | TO-92   | TAPE & AMMO    | 2,000    | 1.Emitter 2.Base 3.Collector |
| KSP2907ACTA  | KSP2907AC      | TO-92   | TAPE & AMMO    | 2,000    | 1.Emitter 2.Collector 3.Base |
| KSP2907ATF   | KSP2907A       | TO-92   | TAPE & REEL    | 2,000    | 1.Emitter 2.Base 3.Collector |

-Note: Affix "-C-" - center collector pin. Suffix "-BU" - Bulk packing, straight lead form.(see package dimensions) Suffix "-TF" - Tape& Reel packing, 0.200 In-Line Spacing lead form. (see package dimensions) SUffix "-TA" - Tape& AMMO packing, 0.200 In-Line Spacing lead form. (see package dimensions)





### TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™ ActiveArray™ Bottomless™ Build it Now<sup>™</sup> CoolFET™  $CROSSVOLT^{\text{TM}}$ DOME™ EcoSPARK™ E<sup>2</sup>CMOS™ EnSigna™ FACT™ FAST® FASTr™ FPS™ FRFET™

The Power Franchise<sup>®</sup> Programmable Active Droop™

FACT Quiet Series™ GlobalOptoisolator™ GTO™ HiSeC™ I<sup>2</sup>C™ i-Lo™ ImpliedDisconnect™ IntelliMAX™ **ISOPLANAR™** LittleFET™ MICROCOUPLER™ MicroFET™ MicroPak™ MICROWIRE™ MSX™ MSXPro™ Across the board. Around the world.™

OCX™ OCXPro™ **OPTOLOGIC**<sup>®</sup> OPTOPLANAR™ PACMAN™ **POP™** Power247™ PowerEdge™ PowerSaver™ PowerTrench<sup>®</sup> **QFET<sup>®</sup>** QS™ QT Optoelectronics™ Quiet Series™ RapidConfigure™ RapidConnect™ uSerDes™ ScalarPump™

SILENT SWITCHER® SMART START™ SPM™ Stealth™ SuperFET™ SuperSOT<sup>™</sup>-3 SuperSOT™-6 SuperSOT<sup>™</sup>-8 SyncFET™ ТСМ™ TinyBoost™ TinyBuck™ TinyPWM™ TinyPower™ TinyLogic® TINYOPTO™ TruTranslation™ UHC™

**UltraFET<sup>®</sup>** UniFET™ VCX™ Wire™

### DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPE-CIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

### As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

# **PRODUCT STATUS DEFINITIONS**

### **Definition of Terms**

| Datasheet Identification | Product Status         | Definition  |
|--------------------------|------------------------|---|
| Advance Information      | Formative or In Design | This datasheet contains the design specifications for<br>product development. Specifications may change in<br>any manner without notice.  |
| Preliminary              | First Production       | This datasheet contains preliminary data, and<br>supplementary data will be published at a later date.<br>Fairchild Semiconductor reserves the right to make<br>changes at any time without notice in order to improve<br>design. |
| No Identification Needed | Full Production        | This datasheet contains final specifications. Fairchild<br>Semiconductor reserves the right to make changes at<br>any time without notice in order to improve design.   |
| Obsolete                 | Not In Production      | This datasheet contains specifications on a product<br>that has been discontinued by Fairchild semiconductor.<br>The datasheet is printed for reference information only.   |
|                          | •                      |   |

Downloaded from Elcodis.com electronic components distributor